

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,
 (b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

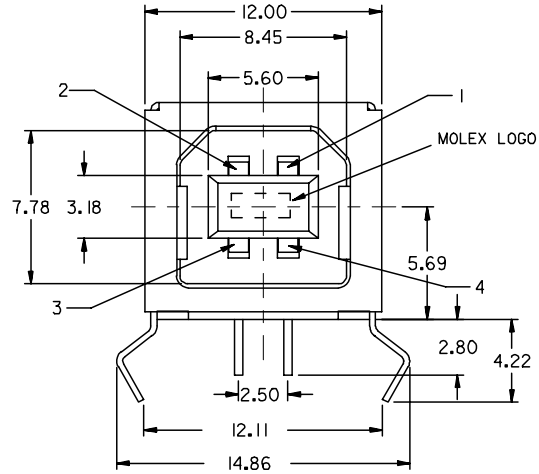
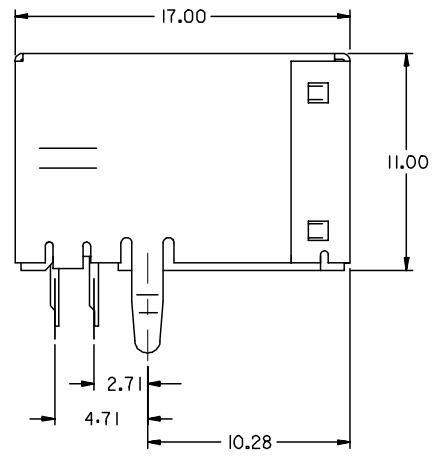
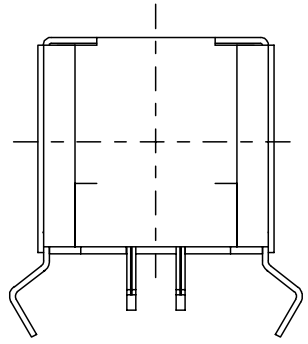
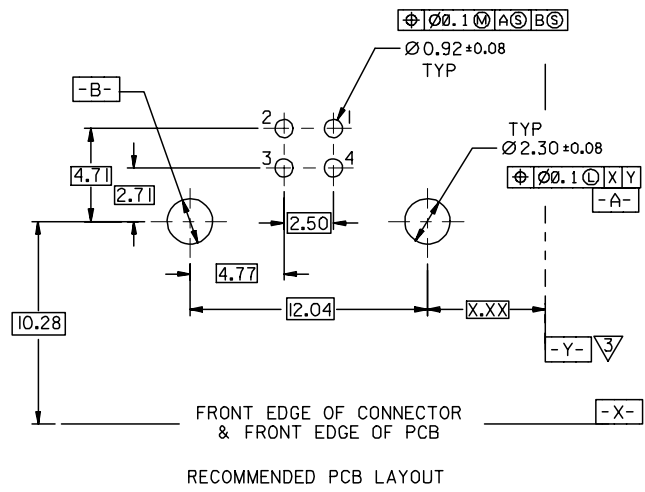
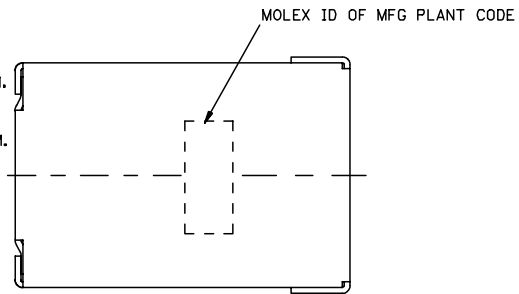
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

METAL SHELL :
 PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

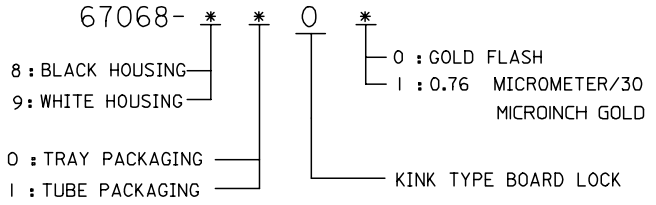
UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



PART NUMBER LEGEND:



NEW RELEASE	QUALITY SYMBOLS
EC NO: SH2005-0142	▽=0
DRWN: DAVID HU 2004/11/5	▽C=0
CHKD: HARVEY 2004/11/25	
APPR: TYAP 2004/11/25	
REV	DESCRIPTION
A	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.25 ± ---
1 PLACE	± 0.25 ± ---
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
HARVEY	2004/11/05
APPROVED BY	DATE
MATERIAL NO.	
DOCUMENT NO.	
SEE NOTES	

SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
USB B TYPE CONNECTOR		
KINK TYPE BOARD LOCK		
(LEAD-FREE)		
MOLEX INCORPORATED		
SD-67068-003		SHEET NO. 1 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,
 (b) POLYESTER, GLASS FIBER FILLED, UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

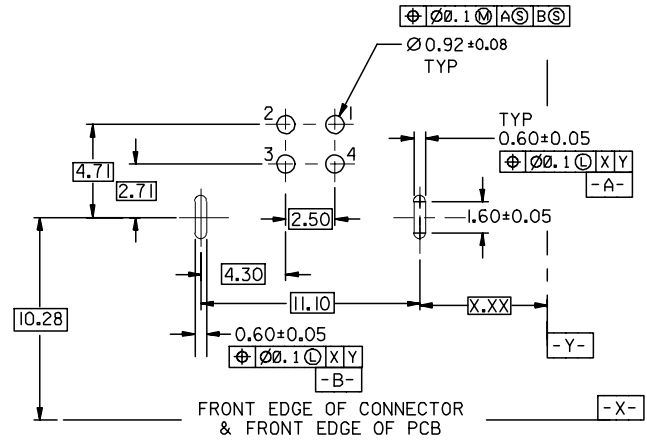
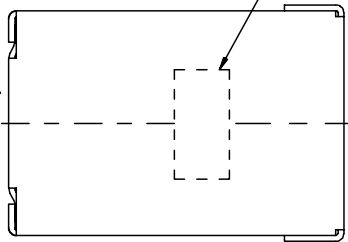
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

METAL SHELL :
 PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

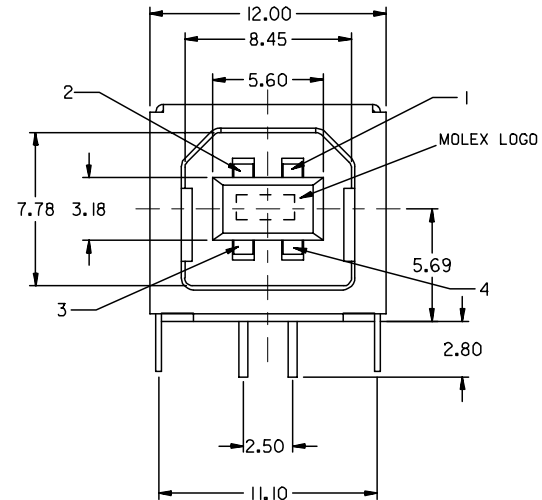
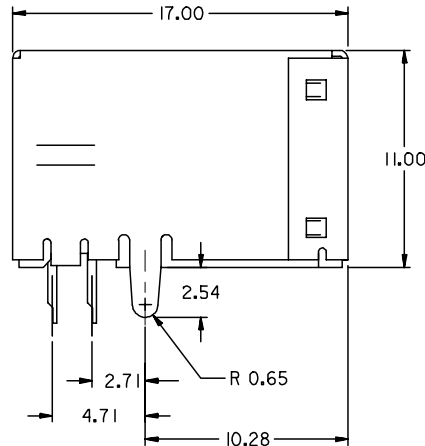
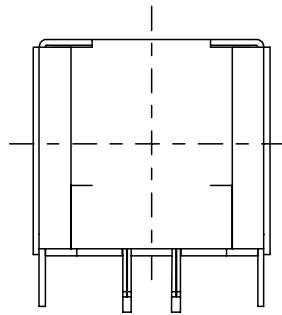
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05
 4 PRODUCT SPECIFICATION ; REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068- * * | * | *
 8 : BLACK HOUSING | 0 : GOLD FLASH
 9 : WHITE HOUSING | 1 : 0.76 MICROMETER/30
 | MICROINCH GOLD
 0 : TRAY PACKAGING | STRAIGHT TAB
 1 : TUBE PACKAGING

NEW RELEASE
 EC NO: SH2005-0142
 DRWN: DAVID HU 2004/11/5
 CHKD: HARVEY 2004/11/25
 APPR: TYAP 2004/11/25

QUALITY SYMBOLS	DESCRIPTION
$\nabla = 0$	
$\nabla C = 0$	
REV	DESCRIPTION
A	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.25 ± --- 2004/11/05
1 PLACE	± 0.25 ± ---
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY	DATE	TITLE	USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
DAVID HU	2004/11/05	MOLEX INCORPORATED		
CHECKED BY	DATE	DOCUMENT NO.	SD-67068-003	
	2004/11/05	SHEET NO. 2		
APPROVED BY	DATE	SEE NOTES		
MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

DRAWN BY		DATE	TITLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
DAVID HU		2004/11/05	USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	4:1	METRIC	
CHECKED BY		DATE	MOLEX INCORPORATED			
		2004/11/05	SD-67068-003			
APPROVED BY		DATE	SEE NOTES			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

8 7 6 5 4 3 2 1

NOTES :
 1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

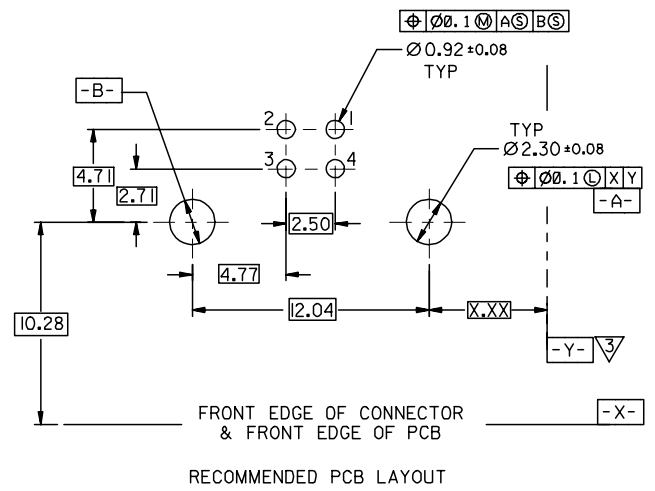
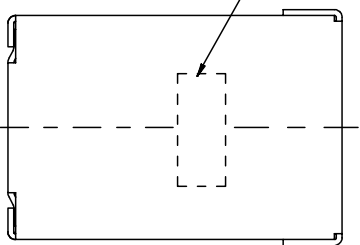
METAL SHELL :
 PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

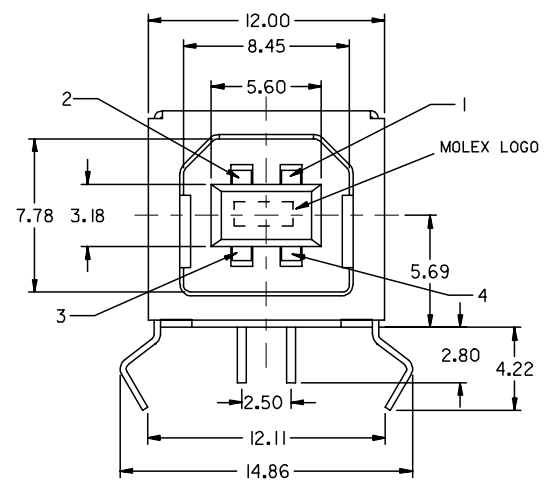
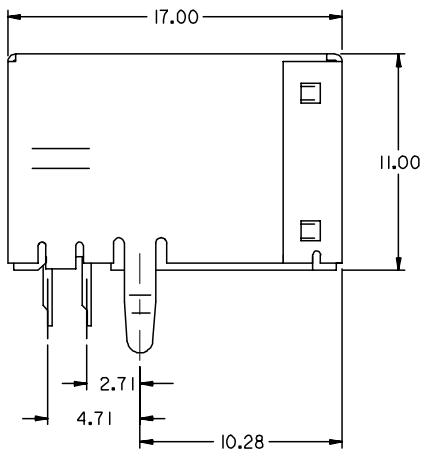
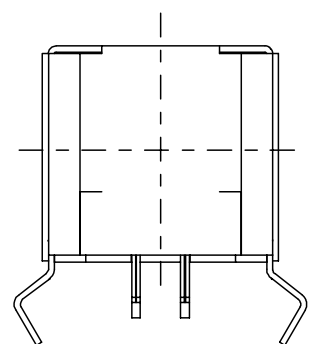
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR
 & FRONT EDGE OF PCB
 RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:
 67068- 7041

				MATERIAL : SEE NOTES		 MOLEX TAIWAN LTD. SHEET 3 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP.USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE)						

DO NOT SCALE DRAWING

ENG. NO SDA-67068-****

EDP NO.

SIMILAR ITEM

CAD FILE : S6706802

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.
(b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

/1.27 MICROMETER MINIMUM.

METAL SHELL :

PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

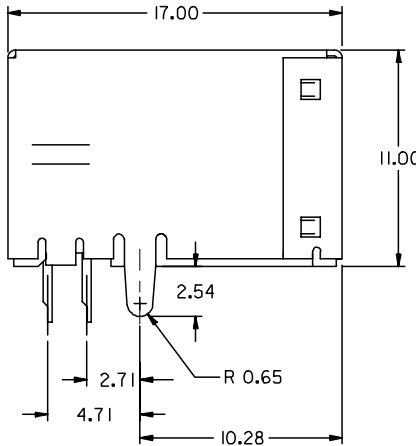
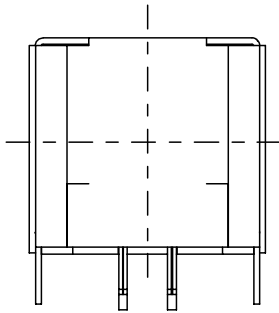
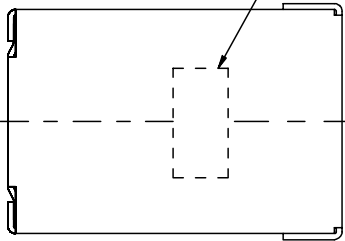
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

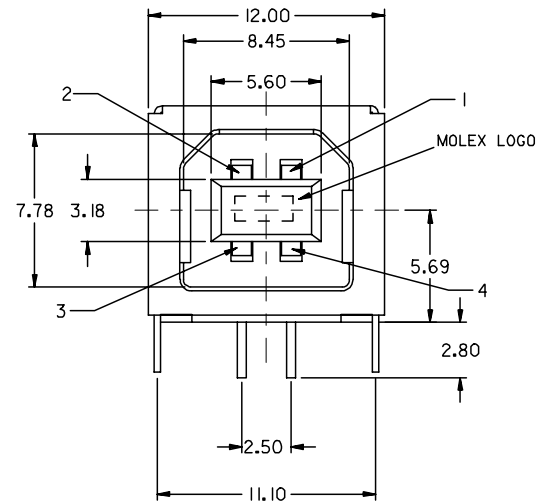
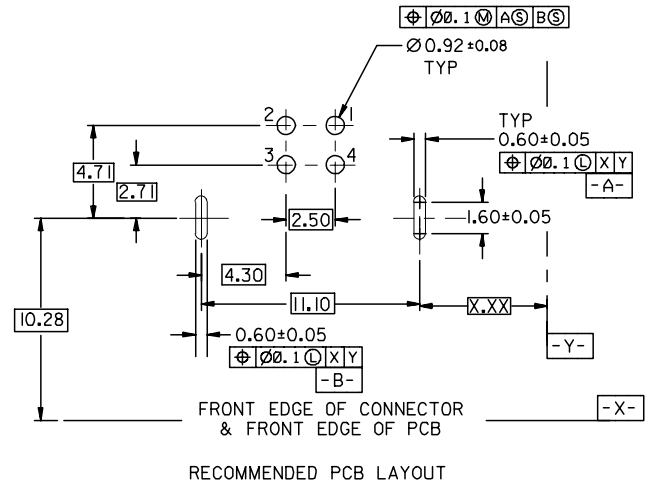
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7051



				MATERIAL : SEE NOTES		 MOLEX TAIWAN LTD. SHEET 4 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP JUSB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)						

NOTES:

1.MATERIAL:

HOUSING:

- (a)HIGH TEMP,NYLON,GLASS FIBRE FILLED,UL94V-0,COLOR: 8BALCK
- (b)POLYESTER(PBT),30% GLASS FIBER FILLED,UL94V-0,COLOR: 9WHITE
- TERMINAL: PHOSPHOR BRONZE
- METAL SHELL: COPPER ALLOY

2.PLATING:

TERMINAL:

- (c)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (d)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (e)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (f)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

METAL SHELL:

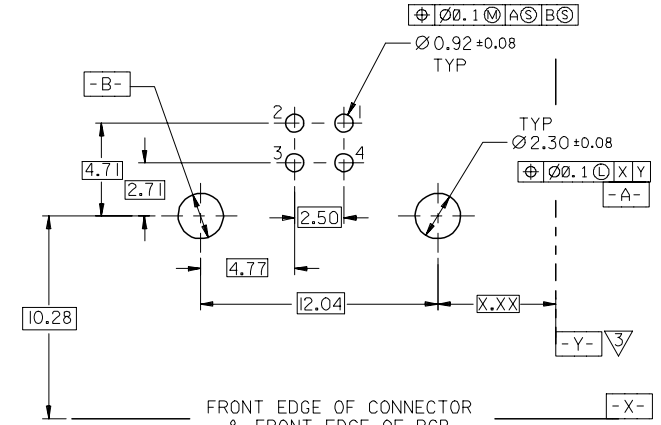
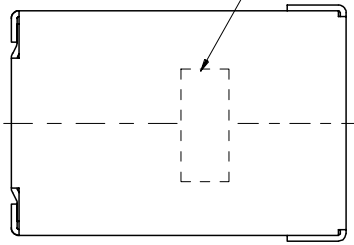
- (g)50 MICROINCH MINIMUM PURE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (h)50 MICROINCH MINIMUM MATTE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

3.DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.

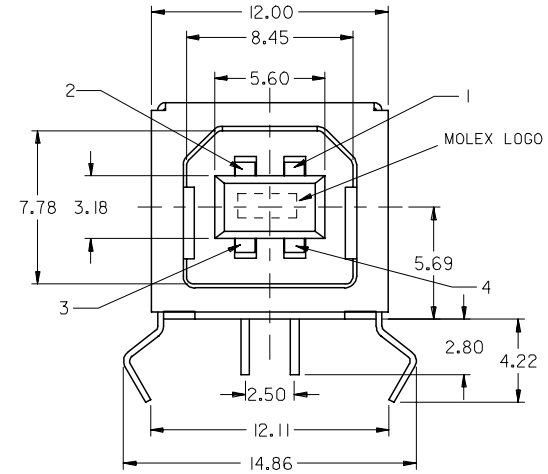
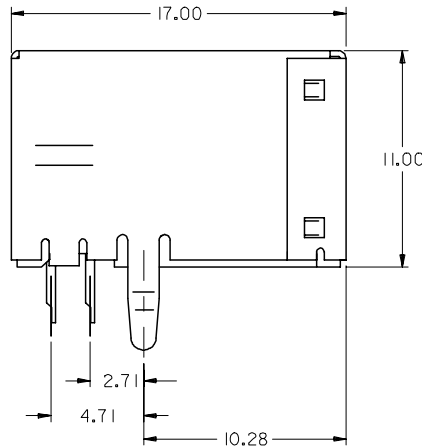
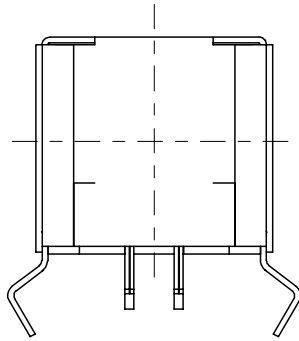
RECOMMENDED PCB THICKNESS : 1.60±0.05

4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB
RECOMMENDED PCB LAYOUT



P/N	HOUSING COLOR	PLATING
67068-8000	BLACK	GOLD FLASH SEE NOTES(2-(c),2-(g))
67068-8001	BLACK	30MICROINCH Au SEE NOTES(2-(d),2-(g))
67068-9000	WHITE	GOLD FLASH SEE NOTES(2-(c),2-(g))
67068-9001	WHITE	30MICROINCH Au SEE NOTES(2-(d),2-(g))
67068-8012	BLACK	30MICROINCH Au SEE NOTES(2-(f),2-(h))
67068-8013	BLACK	GOLD FLASH SEE NOTES(2-(e),2-(h))

REVISED	EC NO: SH2007-0468	2007/01/19
	DRWN:HYE01	2007/01/19
	CHKD:WANG	2007/01/19
	APPR: JNCHEN	2007/01/26
REV	DESCRIPTION	

QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ±---	±---
3 PLACES ±---	±---
2 PLACES ±0.25	±.010
1 PLACE ±0.25	±.010
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
HARVEY	2004/11/05
APPROVED BY	DATE
MATERIAL NO.	
DOCUMENT NO.	
SHEET NO.	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	METRIC	
TITLE		
USB B TYPE CONNECTOR LEAD-FREE		
MOLEX INCORPORATED		
SD-67068-004		1 OF 1
SEE NOTES		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		